



# THE 31st INTERNATIONAL SYMPOSIUM ON SEMICONDUCTOR MANUFACTURING (ISSM)

# CALL FOR PAPERS

**December 7-8, 2026/Ryogoku, Tokyo, Japan**

## Areas of Interest

### Fab Management

Factory Design, Manufacturing Strategy, Manufacturing Control and Execution, Environment, Safety and Health, Carbon Neutral, Intelligent Data Management

### Process Integration

Process/Material Optimization, Yield Enhancement and Methodology, Ultraclean Technology and Contamination Control, Process Monitoring and Control Method, Process/Metrology Equipment, Design for Manufacturing, Innovative Manufacturing Technology

### 3D, Chiplets & Advanced Packaging

3D Integration, Chiplets Packaging and Advanced Packaging Technology

## Highlighted Theme:

- Robotics and AI Solution
- Next Generation Fab
- Sustainable Manufacturing and Promotion of Global Environmental Conservation
- Exploring New Frontiers from Chip Design to Testing
- 3D and Chiplets Packaging
- Substrate Surface Cleaning Technology (with the cooperation of the Interfacial Nano Electrochemistry: INE)

## Important Dates

Abstract Submission Due: **July 31, 2026**

Notification of Paper Acceptance: **September 30, 2026**

Final Paper Due **October 30, 2026**

Paper Submission & Guidelines:

<https://issm.semiconportal.net/>

